

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (original) An MCM device comprising a flat thin insulation substrate having parallel top and bottom surfaces; a plurality of laterally displaced conductive vias extending between said top and bottom surfaces; a flip chip semiconductor die having top and bottom surfaces and having at least first and second electrodes on said top and bottom surfaces; said first and second electrodes having contacts on said die bottom surface connected to respective ones of said plurality of vias; a second flip chip semiconductor die having top and bottom surfaces and having at least first and second electrodes on said top and bottom surfaces; said first and second electrodes of said second die connected to respective ones of said plurality of vias; and a moldable conductive electrode extending over the top of said substrate and over the upper most surfaces of said die and in contact therewith, and further connected to a respective one of said vias.

Claims 2-10 (canceled).

11. (original) The device of claim 1, wherein said moldable conductive electrode has an upper surface which contains parallel grooves which define fins in said upper surface of said conductive electrode

Claim 12 (canceled).

13. (currently amended) An MCM device comprising:
a flat thin insulation substrate having parallel top and bottom surfaces;
a plurality of laterally displaced conductive vias extending between said top and bottom surfaces;

a flip chip semiconductor die having top and bottom surfaces and having at least first and second electrodes on said top and bottom surfaces, wherein said first and second electrodes have contacts on said die bottom surface connected to respective ones of said plurality of vias; and

an insulation cap covering said die and covering the top surface of said substrate, wherein said insulation cap has a peripheral rim which receives the outer peripheral edge of said substrate but does not reach said bottom surface, and wherein adjacent vertical surfaces of said peripheral rim and said outer peripheral edge of said substrate have cooperating projections and depressions to define a mold lock.

14. (original) The device of claim 1, which further includes respective solder balls connected to the bottoms of said conductive vias.

Claims 15-18 (canceled).

19. (original) The device of claim 13, which further includes respective solder balls connected to the bottoms of said conductive vias.

20. (previously presented) The device of claim 13, further comprising:

at least one passive component which is beneath said insulation cap, wherein said at least one passive component has at least one dimension which is longer than its other dimensions, and wherein said at least one dimension is disposed perpendicular to said top surface of said substrate.

21. (previously presented) The device of claim 20, wherein said insulation cap has a plurality of fins extending from a free surface thereof.

22. (previously presented) The device of claim 21, wherein said at least one passive component is disposed laterally between a respective pair of said fins.